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# Product Termination Notification

Product Group: SIL/Mon Mar 25, 2024/PTN-SIL-020-2024-REV-0



## Conversion to Copper (Cu) Wire – SQ2389ES

For further information, please contact your regional Vishay office.

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**Description of Change:** The affected part number listed in this notification will be converted to a Copper wire material set. The new ordering code is SQ2389CES-T1\_GE3 which has Identical silicon technology and silicon die design as SQ2389ES. Small changes to the data sheet AC parameters are a consequence of lot to lot variation and/or updated characterization methods (reference: SQ2389CES Doc # 62212 Rev.A). Device performance in the application will not be impacted. There will be no change to the wafer fab location.

**Reason for Change:** Standardization of materials

**Expected Influence on Quality/Reliability/Performance:** None

**Part Numbers/Series/Families Affected:** SQ2389ES-T1\_GE3, SQ2389ES-T1\_BE3,

**Vishay Brand(S):** Vishay Siliconix

#### Time Schedule:

Last Time Buy Date: Sat Sep 28, 2024

Last Time Ship Date: Sat Mar 29, 2025

**Sample Availability:** Qualified samples of replacement product are available on request

**Product Identification:** SQ2389CES-T1\_GE3

**Qualification Data:** AEC Q101 qualification data of replacement product is available. Qualification PPAP is available now.

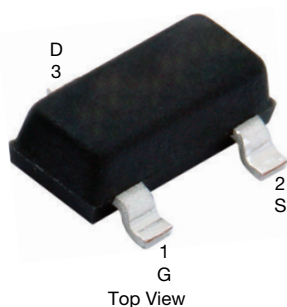
**This PTN is considered approved, without further notification, unless we receive specific customer concerns before Sat Sep 28, 2024 or as specified by contract.**

**Issued By:** Lance Gurrola, automostechsupport@vishay.com



## Automotive P-Channel 40 V (D-S) 175 °C MOSFET

SOT-23 (TO-236)

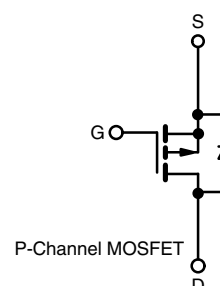


Marking Code: 9UYXX

PRODUCT SUMMARY	
$V_{DS}$ (V)	-40
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS} = -10$ V	0.094
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS} = -4.5$ V	0.188
$I_D$ (A)	-4.1
Configuration	Single

## FEATURES

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 %  $R_g$  and UIS tested
- Material categorization:  
for definitions of compliance please see  
[www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

AUTOMOTIVE  
GRADERoHS  
COMPLIANT  
HALOGEN  
FREE

ORDERING INFORMATION	
Package	SOT-23
Lead (Pb)-free and halogen-free	SQ2389CES (for detailed order number please see <a href="http://www.vishay.com/doc?79771">www.vishay.com/doc?79771</a> )

ABSOLUTE MAXIMUM RATINGS ( $T_C = 25$ °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		$V_{DS}$	-40	V
Gate-source voltage		$V_{GS}$	$\pm 20$	
Continuous drain current	$T_C = 25$ °C	$I_D$	-4.1	A
	$T_C = 125$ °C		-2.4	
Continuous source current (diode conduction)		$I_S$	-3.6	
Pulsed drain current <sup>a</sup>		$I_{DM}$	-16	
Single pulse avalanche current	$L = 0.1$ mH	$I_{AS}$	-12	
		$E_{AS}$	7.2	mJ
Maximum power dissipation	$T_C = 25$ °C	$P_D$	3	W
	$T_C = 125$ °C		1	
Operating junction and storage temperature range		$T_J, T_{stg}$	-55 to +175	°C

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-ambient	PCB mount <sup>b</sup>	$R_{thJA}$	166	°C/W
Junction-to-foot (drain)		$R_{thJF}$	50	

## Notes

- a. Pulse test; pulse width  $\leq 300$   $\mu$ s, duty cycle  $\leq 2$  %  
b. When mounted on 1" square PCB (FR4 material)



SPECIFICATIONS (T <sub>C</sub> = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = -250 μA		-40	-	-	V
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250 μA		-1.5	-2.0	-2.5	
Gate-source leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = -40 V	-	-	-1	μA
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = -40 V, T <sub>J</sub> = 125 °C	-	-	-50	
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = -40 V, T <sub>J</sub> = 175 °C	-	-	-150	
On-state drain current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = -10 V	V <sub>DS</sub> ≤ -5 V	-10	-	-	A
Drain-source on-state resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10 V	I <sub>D</sub> = -3 A	-	0.084	0.094	Ω
		V <sub>GS</sub> = -10 V	I <sub>D</sub> = -3 A, T <sub>J</sub> = 125 °C	-	-	0.144	
		V <sub>GS</sub> = -10 V	I <sub>D</sub> = -3 A, T <sub>J</sub> = 175 °C	-	-	0.169	
		V <sub>GS</sub> = -4.5 V	I <sub>D</sub> = -3 A	-	0.140	0.188	
Forward transconductance <sup>b</sup>	g <sub>fs</sub>	V <sub>DS</sub> = -10 V, I <sub>D</sub> = -3 A		-	5	-	S
Dynamic <sup>b</sup>							
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = -20 V, f = 1 MHz	-	414	455	pF
Output capacitance	C <sub>oss</sub>			-	80	100	
Reverse transfer capacitance	C <sub>rss</sub>			-	42	54	
Total gate charge <sup>c</sup>	Q <sub>g</sub>	V <sub>GS</sub> = -10 V	V <sub>DS</sub> = -20 V, I <sub>D</sub> = -3 A	-	8.2	12	nC
Gate-source charge <sup>c</sup>	Q <sub>gs</sub>			-	1.1	-	
Gate-drain charge <sup>c</sup>	Q <sub>gd</sub>			-	3.0	-	
Gate resistance	R <sub>g</sub>	f = 1 MHz		3.1	4.1	7	Ω
Turn-on delay time <sup>c</sup>	t <sub>d(on)</sub>	V <sub>DD</sub> = -20 V, R <sub>L</sub> = 6.7 Ω I <sub>D</sub> ≅ -3 A, V <sub>GEN</sub> = -10 V, R <sub>g</sub> = 1 Ω		-	7	10	ns
Rise time <sup>c</sup>	t <sub>r</sub>			-	12	16	
Turn-off delay time <sup>c</sup>	t <sub>d(off)</sub>			-	16	20	
Fall time <sup>c</sup>	t <sub>f</sub>			-	4	8	
Source-Drain Diode Ratings and Characteristics <sup>b</sup>							
Pulsed current <sup>a</sup>	I <sub>SM</sub>			-	-	-10	A
Forward voltage	V <sub>SD</sub>	I <sub>F</sub> = -1.5 A, V <sub>GS</sub> = 0 V		-	-0.8	-1.2	V
Body diode reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = -2 A, di/dt = 100 A/μs		-	17	34	ns
Body diode reverse recovery charge	Q <sub>rr</sub>			-	14	28	nC
Reverse recovery fall time	t <sub>a</sub>			-	14	-	ns
Reverse recovery rise time	t <sub>b</sub>			-	3	-	
Body diode peak reverse recovery current	I <sub>RM(REC)</sub>					-	-1.99

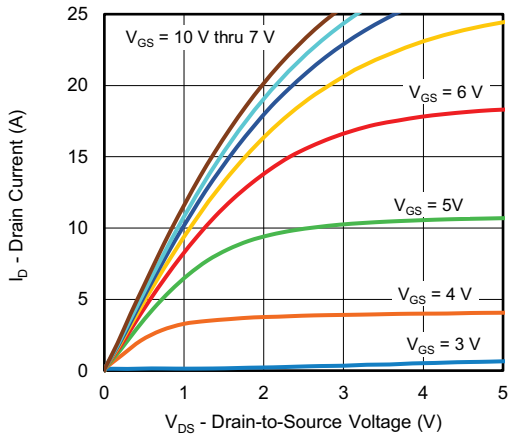
**Notes**

- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$   
b. Guaranteed by design, not subject to production testing  
c. Independent of operating temperature

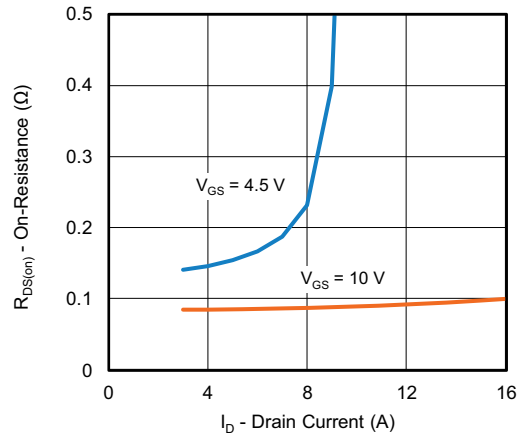
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



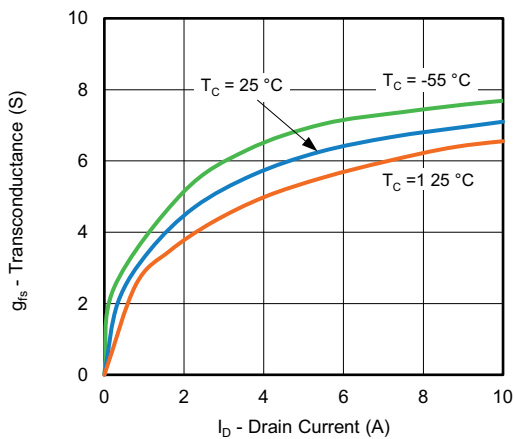
**TYPICAL CHARACTERISTICS** ( $T_A = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted)



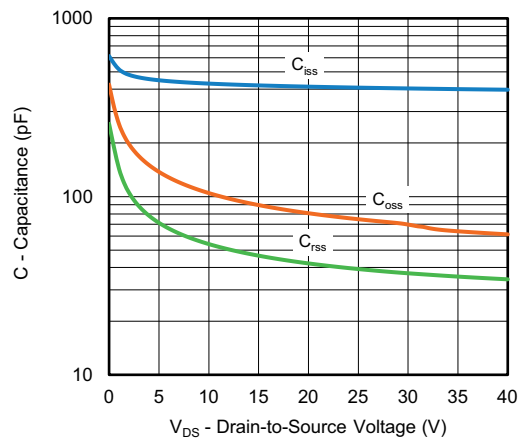
**Output Characteristics**



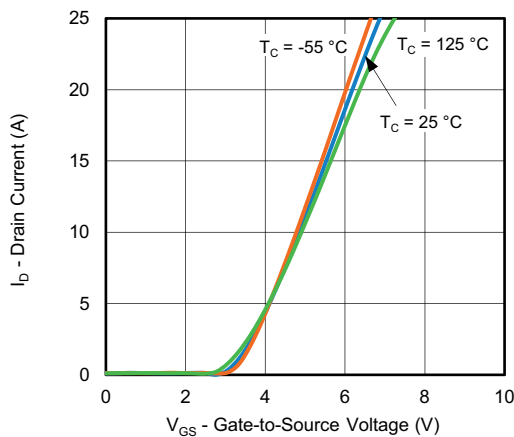
**On-Resistance vs. Drain Current**



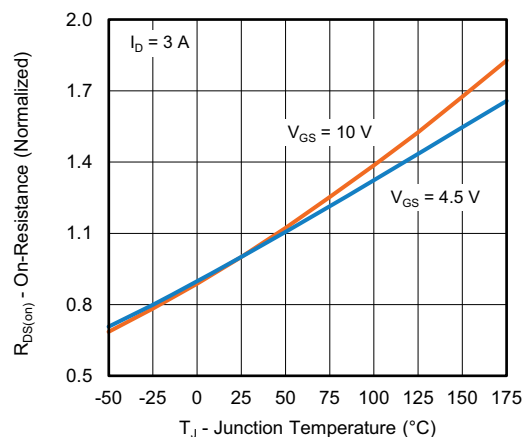
**Transconductance**



**Capacitance**



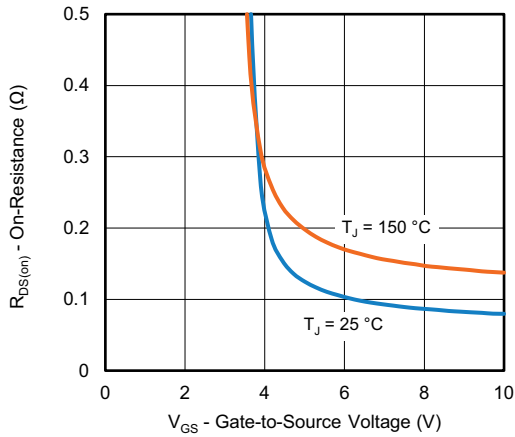
**Transfer Characteristics**



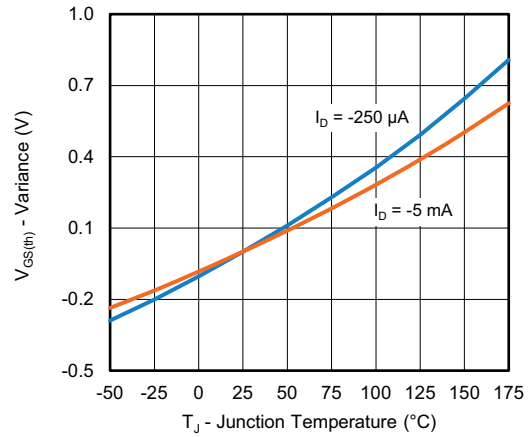
**On-Resistance vs. Junction Temperature**



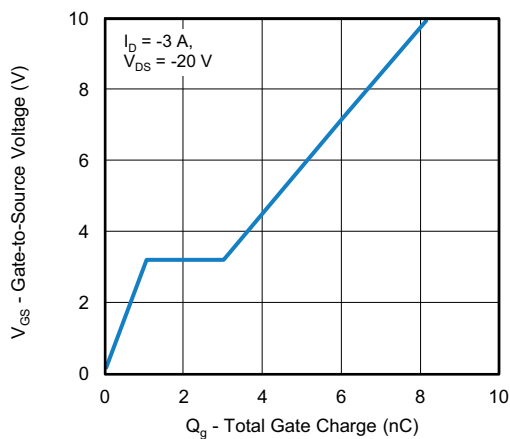
**TYPICAL CHARACTERISTICS** ( $T_A = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted)



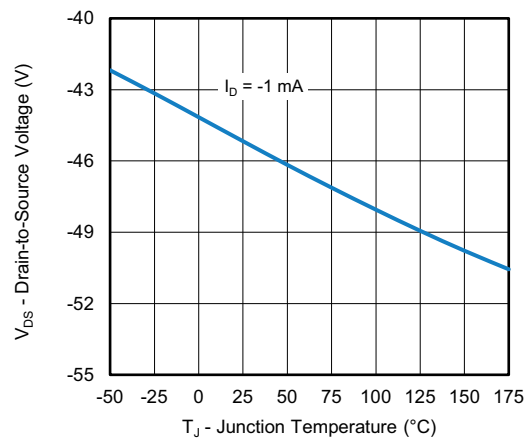
**On-Resistance vs. Gate-Source Voltage**



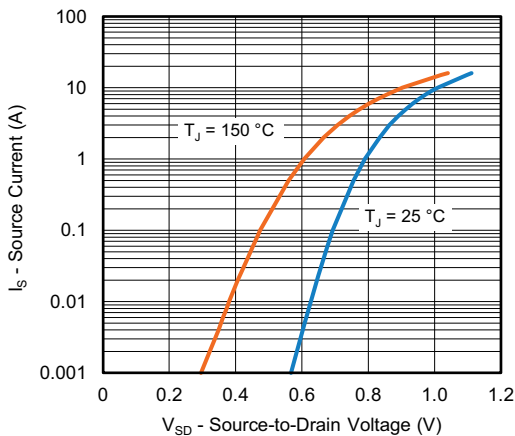
**Threshold Voltage**



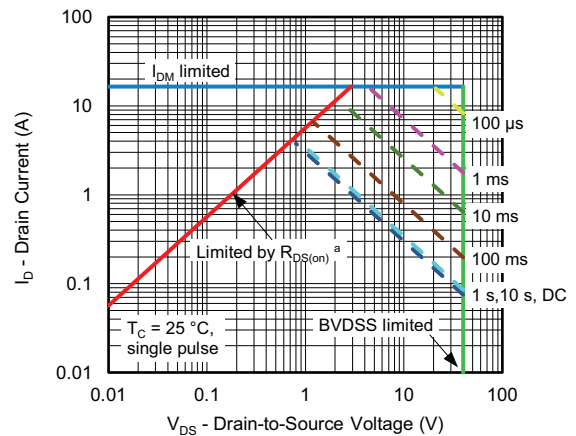
**Gate Charge**



**Drain Source Breakdown vs. Junction Temperature**



**Source-Drain Diode Forward Voltage**



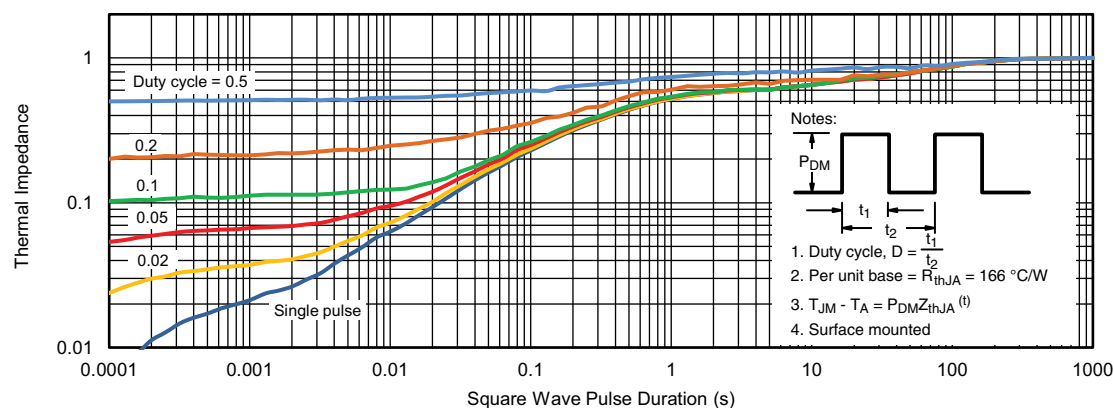
**Safe Operating Area**

**Note**

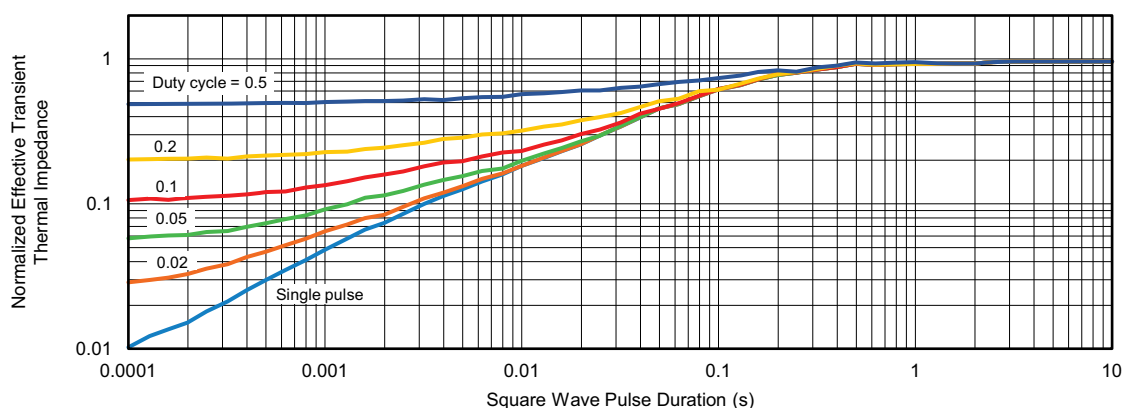
a.  $V_{GS} >$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified



**THERMAL RATINGS** ( $T_A = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted)



**Normalized Thermal Transient Impedance, Junction-to-Ambient**



**Normalized Thermal Transient Impedance, Junction-to-Foot**

**Notes**

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient ( $25\text{ }^{\circ}\text{C}$ )
  - Normalized Transient Thermal Impedance Junction-to-Foot ( $25\text{ }^{\circ}\text{C}$ )are given for general guidelines only to enable the user to get a “ball park” indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions



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